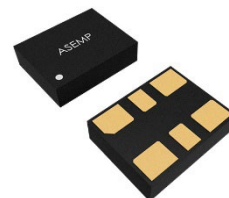


Description

The Abracon ASEMP series is a programmable MEMS oscillator, with a continuous operating power supply ranging from 2.25V to 3.6V. This series features low power consumption, a wide frequency range, excellent phase noise, tight stabilities, and short lead times for industrial, consumer, and other applications. The ASEMP series comes in a 3.2 x 2.5 mm compact package with CMOS, HCSL, LVDS, or LVPECL output logic.



Features

- Low Power Consumption for high-speed communication
- Exceptional Stability Over Temp. at -40 to +85°C, ± 10 ppm
- Extended Operating Temperature at -55 to +125°C, ± 25 ppm
- MIL-STD-883 shock and vibration compliant
- Durable QFN Plastic Compact Packaging
- Enable or Disable Tri-state function
- Low jitter (Period jitter RMS and Phase jitter RMS)
- High power supply noise reduction, -50dBc
- [REACH/RoHS II Compliant](#) | [MSL Level 1](#)

Applications

- Storage Area Networks (SATA, SAS, Fiber Channel)
- Passive Optical Networks (EPON, 10G-EPON, GPON, 10G-PON)
- Ethernet (1G, 10GBASE-T, KR/LR/SR, FCoE)
- PCI Express
- Display port

Key Electrical Specifications - Continuous Vdd: 2.5V - 0.25V to 3.3V + 0.3V

Parameters		Min.	Typ.	Max.	Units	Notes
Frequency Range	CMOS	2.3000		170.0000	MHz	-20 ~ +70°C -40 ~ +85°C
	CMOS	3.3000		170.0000		-40 ~ +105°C -55 ~ +125°C
	LVPECL	2.3000		460.0000		-20 ~ +70°C -40 ~ +85°C -40 ~ +105°C
	LVDS	2.3000		460.0000		-20 ~ +70°C -40 ~ +85°C -40 ~ +105°C
	HCSL	2.3000		460.0000		-20 ~ +70°C -40 ~ +85°C -40 ~ +105°C
Operating Temperature		-20		+70	°C	See options
Storage Temperature		-55		+150	°C	
Overall Frequency Stability [Note 1]		-50		+50	ppm	See options
Supply Voltage (Vdd)		+2.25		+3.6	V	
Startup Time				5	ms	
Enable Time				20	ns	STD (Tri-state)

Key Electrical Specifications Cont. - CMOS, LVPECL, LVDS, and HCSL

Parameters	Min.	Typ.	Max.	Unit	Notes
Disable Time			5	ns	
Disable Current		20	22	mA	STD (Tri-state)
Tri-state Function (Enable/Disable)	"1" ($V_{IH} \geq 0.75 \cdot V_{DD}$) or Open: Oscillation "0" ($V_{IL} < 0.25 \cdot V_{DD}$): Hi Z			V	40kΩ pull-up resistor embedded
Aging	-5.0		+5.0	ppm	First year

Note 1: Includes post reflow frequency accuracy, temperature stability, load pulling and power supply variation.

Key Electrical Specifications - CMOS

Parameters		Min.	Typ.	Max.	Units	Notes
Supply Current (I _{DD})			31	35	mA	CL=15pF, 125MHZ
Output Logic Level	V _{OH}	0.9*V _{DD}			V	I=±6mA
	V _{OL}			0.1*V _{DD}	V	
Rise Time	T _r		1.1	2.0	ns	CL=15pF 20% to 80%
Fall Time	T _f		1.3	2.0	ns	
Duty Cycle		45		55	%	
Integrated Phase Jitter (J _{PH})			0.30	2	ps	200kHz ~ 20MHz@125MHz
			0.38	2		100kHz ~ 20MHz@125MHz
			1.70	2		12kHz ~ 20MHz@125MHz
Period Jitter RMS (J _{PER})			3.0		ps	

Key Electrical Specifications - LVPECL

Parameters		Min.	Typ.	Max.	Units	Notes
Supply Current (I _{dd})			56.5	58	mA	RL= 50Ω
Output Logic Level	V _{OH}	V _{dd} -1.08			V	RL= 50Ω
	V _{OL}			V _{dd} -1.55	V	
Peak to Peak Output Swing (V _{pp})			800		mV	Single ended
Rise Time:	T _r		250		ps	RL=50Ω , CL=0pF 20% to 80%
Fall Time:	T _f		250			
Duty Cycle		48		52	%	Differential
Integrated Phase Jitter (J _{PH})			0.25	2	ps	200kHz~20MHz@156.25MHz
			0.38	2		100kHz~20MHz@156.25MHz
			1.70	2		12kHz ~ 20MHz@156.25MHz
Period Jitter RMS (J _{PER})			2.5		ps	

Key Electrical Specifications - LVDS

Parameters		Min.	Typ.	Max.	Units	Notes
Supply Current (I _{dd})			29	32	mA	RL= 100Ω
Output Offset Voltage (ΔV _{OS})		1.125		1.4	V	RL= 100Ω differential
Delta Offset Voltage (ΔV _{OS})				50	mV	
Peak to Peak Output Swing (V _{pp})			350		mV	Single ended
Rise Time:	T _r		200		ps	RL=50Ω , CL=2pF 20% to 80%
Fall Time:	T _f		200			
Duty Cycle		48		52	%	Differential
Integrated Phase Jitter (J _{PH})			0.28	2	ps	200kHz~20MHz@156.25MHz
			0.40	2		100kHz~20MHz@156.25MHz
			1.70	2		12kHz ~ 20MHz@156.25MHz
Period Jitter RMS (J _{PER})			2.5		ps	

Key Electrical Specifications - HCSL

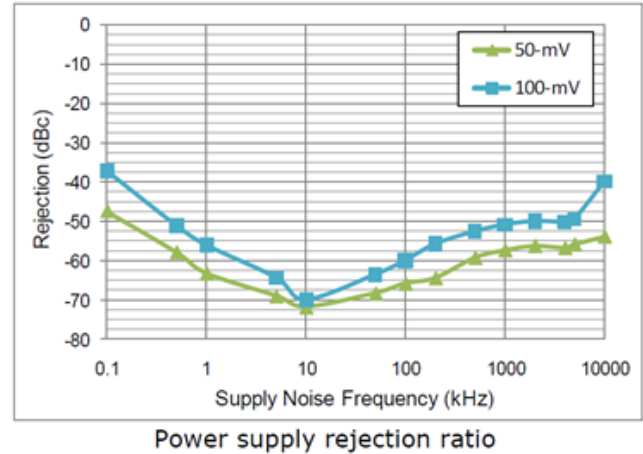
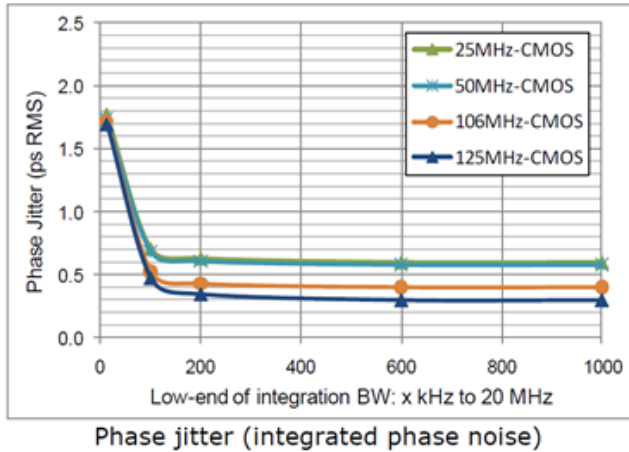
Parameters		Min.	Typ.	Max.	Units	Notes
Supply Current (I _{dd})			40	42	mA	RL= 50Ω
Output Logic Level	V _{OH}	0.725			V	RL= 50Ω
	V _{OL}			0.1	V	
Peak to Peak Output Swing (V _{pp})			750		mV	Single ended
Rise Time:	Tr	200		400	ps	RL=50Ω , CL=2pF 20% to 80%
Fall Time:	Tf	200		400		
Duty Cycle		48		52	%	Differential
Integrated Phase Jitter (J _{PH})			0.25	2	ps	200kHz ~ 20MHz@156.25MHz
			0.37	2		100kHz ~ 20MHz@156.25MHz
			1.70	2		12kHz ~ 20MHz@156.25MHz
Period Jitter RMS (J _{PER})			2.5		ps	

Absolute Maximum Ratings

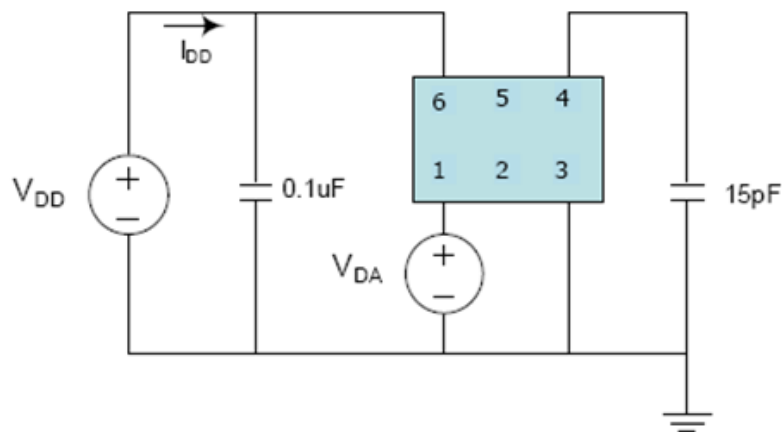
Item	Min.	Max.	Units
Supply Voltage	-0.3	+4.0	V
Input Voltage	-0.3	V _{dd} +0.3	V
Junction Temp.		+150	°C
Storage Temp.	-55	+150	°C
Soldering Temp.		+260	°C
ESD			
HBM		4,000	V
MM		400	
CDM		1,500	

Key Nominal Performance Parameters (Unless specified otherwise: $T=25^{\circ}\text{C}$, $V_{DD}=3.3\text{V}$)

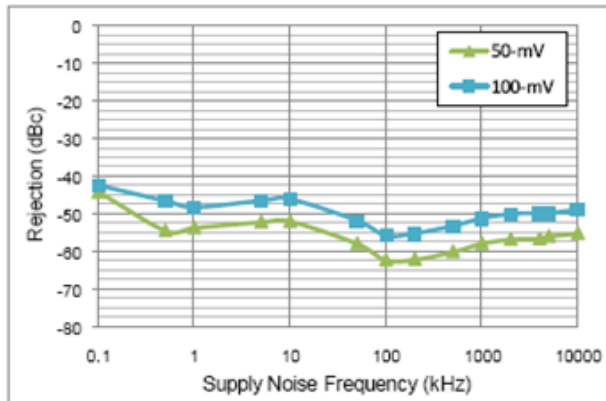
CMOS OUTPUT



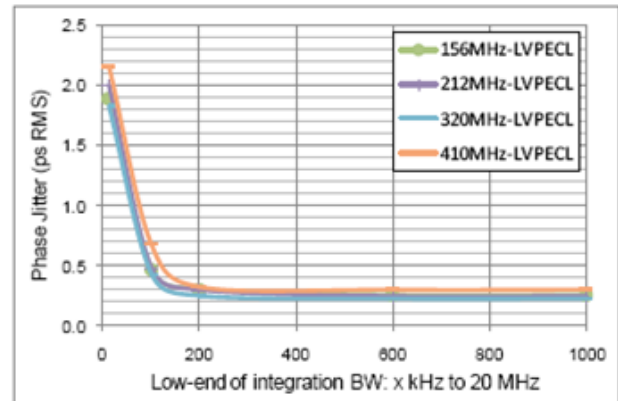
Test Circuit



LVPECL OUTPUT

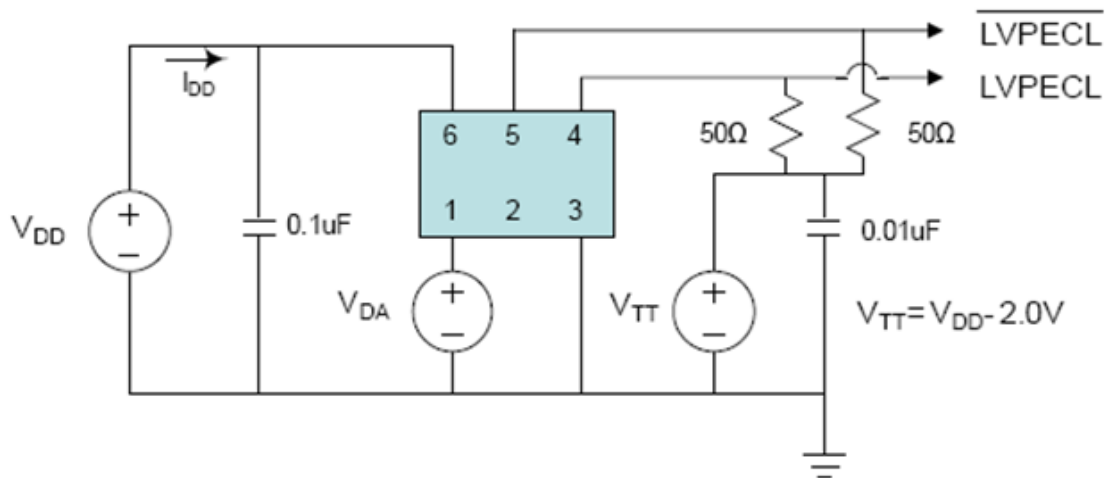


Power supply rejection ratio

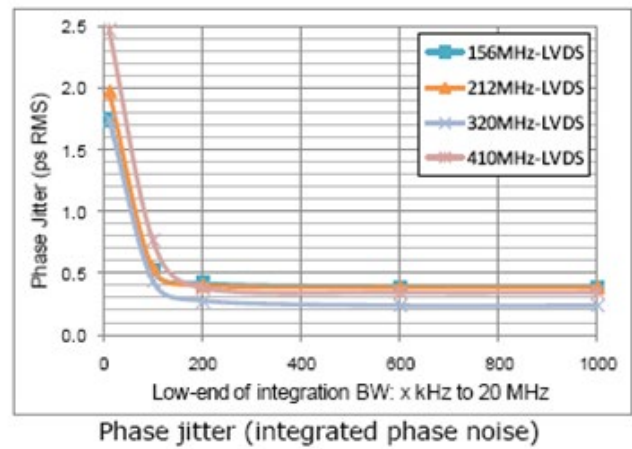
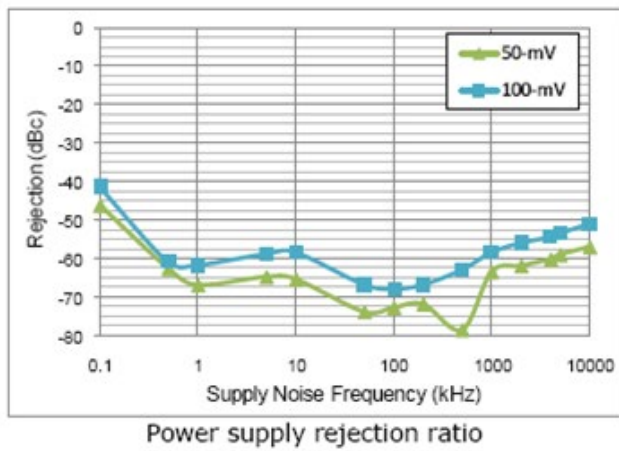


Phase jitter (integrated phase noise)

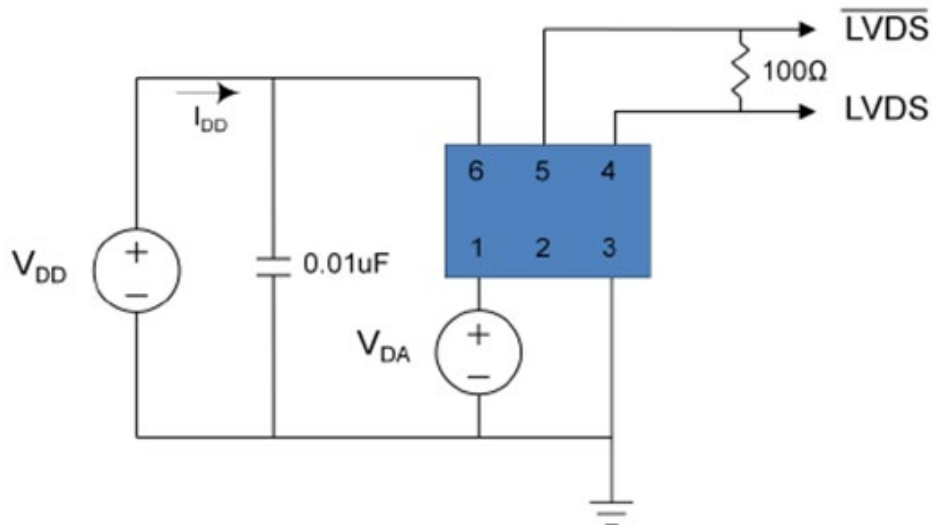
Test Circuit



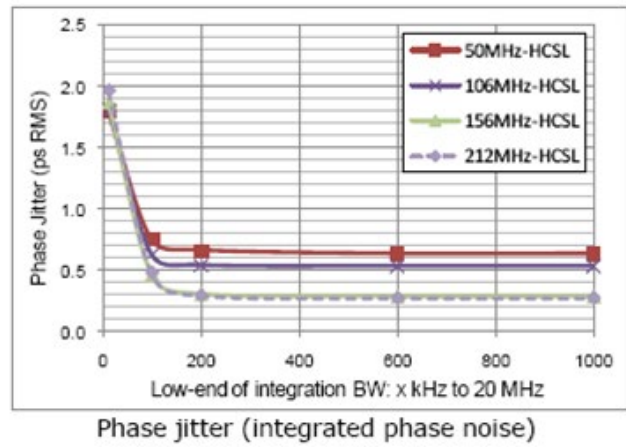
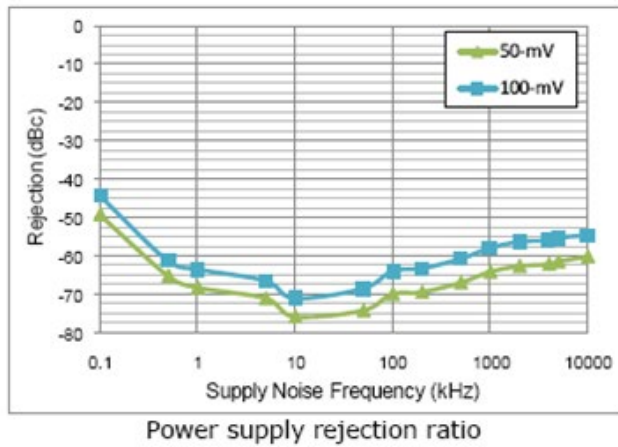
LVDS OUTPUT



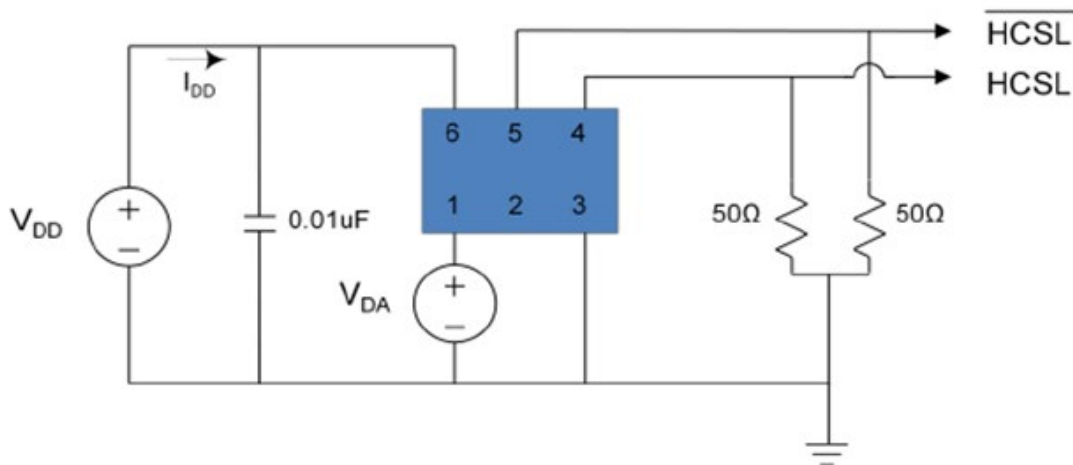
Test Circuit



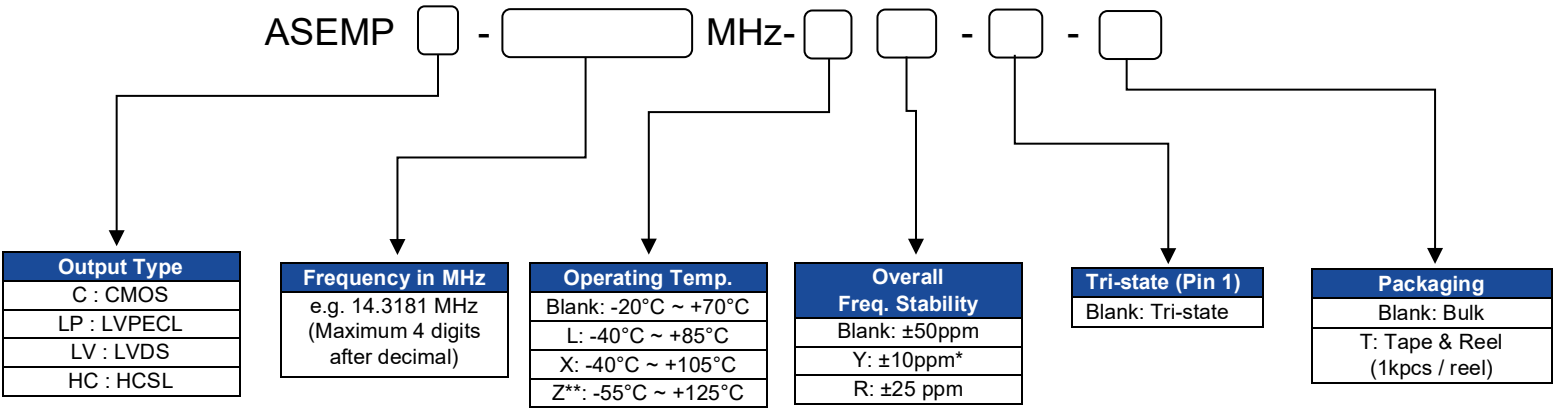
HCSL OUTPUT



Test Circuit

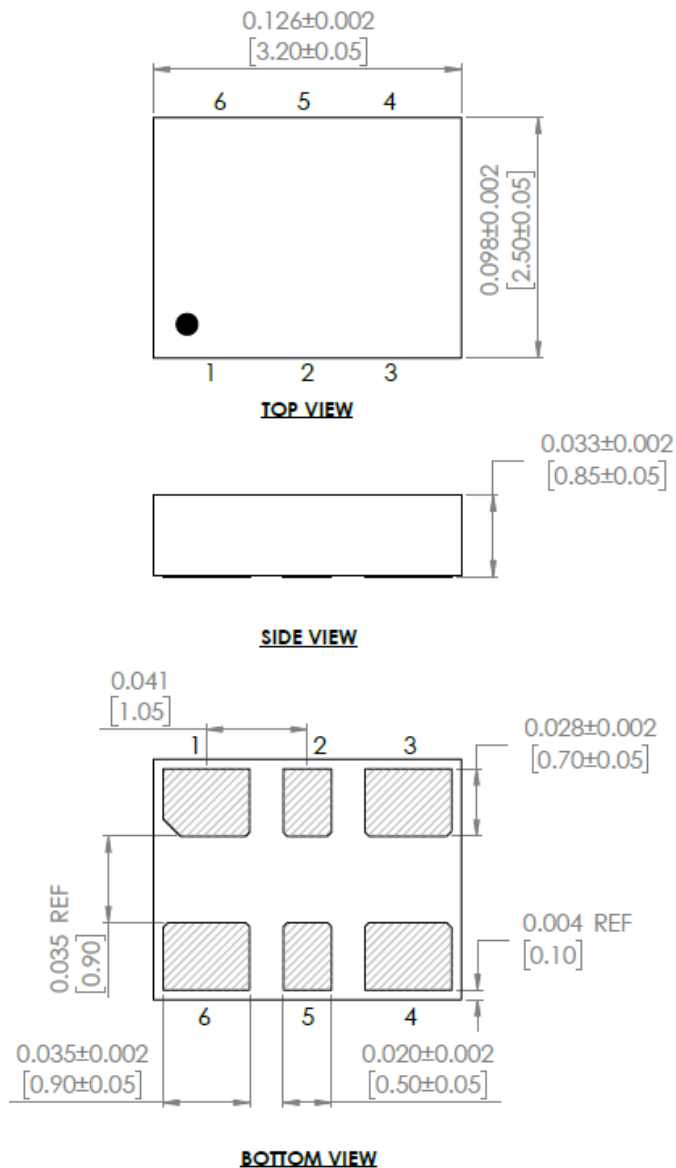


Options and Part Identification (left blank if standard)

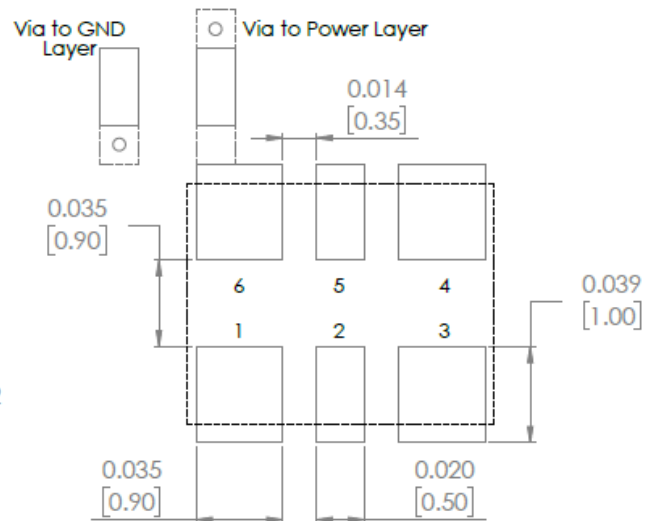


* Temp option L, X or -20°C ~ +70°C, only
** CMOS output only

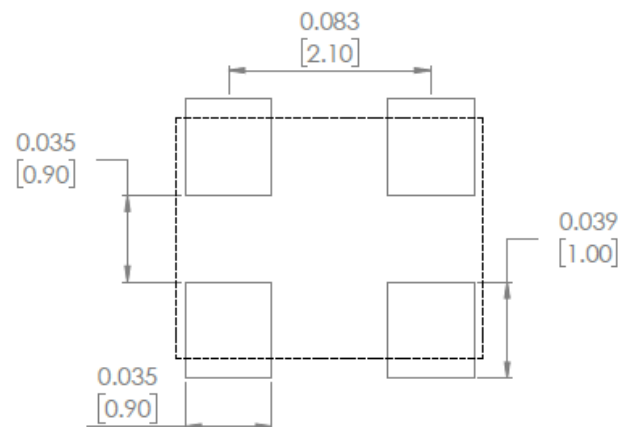
Mechanical Dimensions



Recommended Land Pattern FOR LVPECL, LVDS, HCSL



Recommended Land Pattern FOR CMOS



Note: Recommended using an approximately 0.01uF bypass capacitor between pin 6 and 3.

Dimensions: Inches[mm]

Pin #	Function
1	Tri-State
2	NC
3	GND
4	Output
5	NC (CMOS) Output (LVPECL, LVDS, HCSL)
6	Vdd

Reflow Profile [JEDEC J-STD-020]

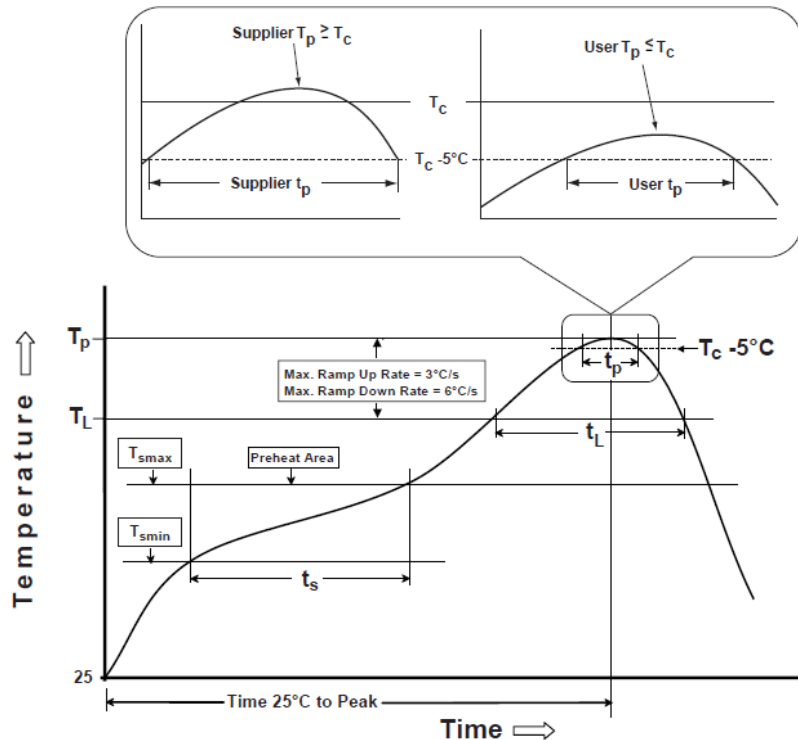


Table 1

SnPb Eutectic Process
Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2

Pb-Free Process
Classification Temperatures (T_c)

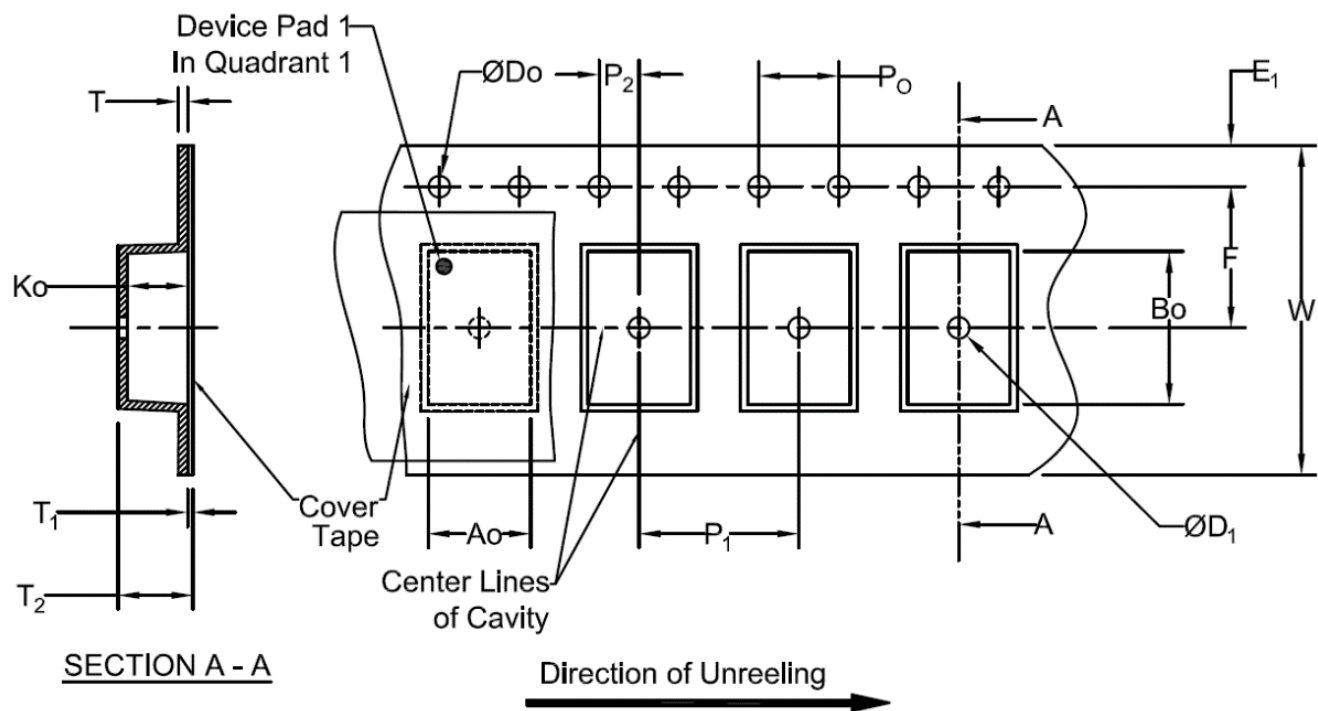
Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat / soak		
Temperature minimum (T_{smin})	100°C	150°C
Temperature maximum (T_{smax})	150°C	200°C
Time (T_{smin} to T_{smax}) (t_s)	60 - 120 sec.	60 - 120 sec.
Average ramp-up rate (T_{smax} to T_p)	3°C/sec. max	3°C/sec. max
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60 - 150 sec.	60 - 150 sec.
Peak package body temperature (T_p)*	see Table 1	see Table 2
Time (t_p)** within 5°C of the specified classification temperature (T_c)	20 sec.	30 sec.
Ramp-down rate (T_p to T_{smax})	6°C/sec. max	6°C/sec. max
Time 25°C to peak temperature	6 min. max	8 min. max
Reflow cycles	2 max	2 max

*Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.**Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

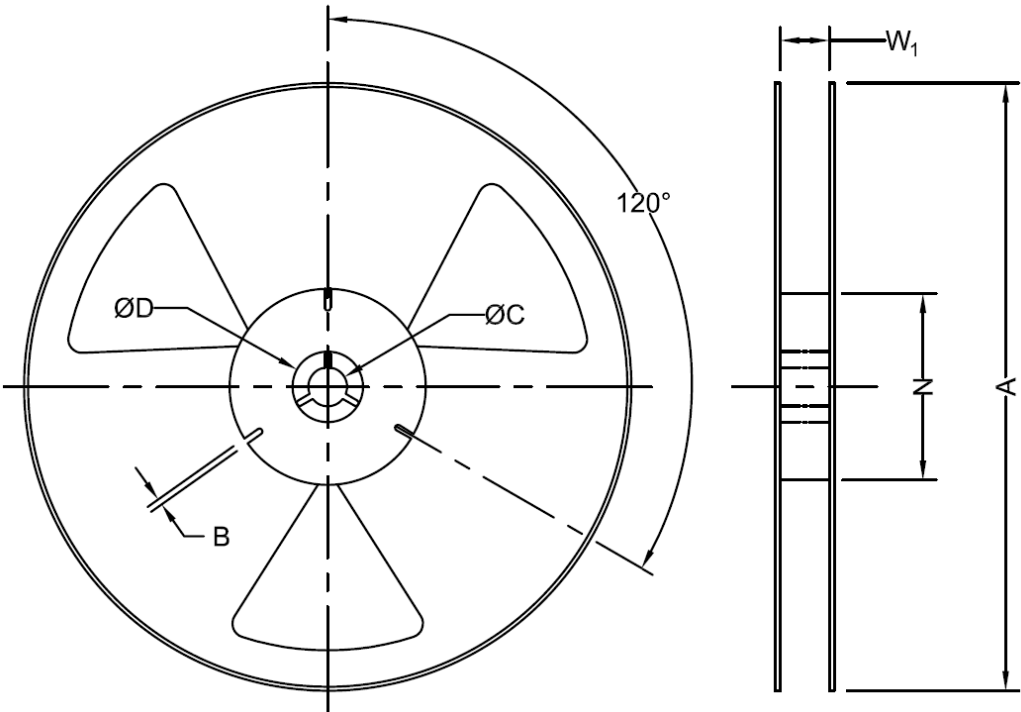
Packaging

T: 1,000pcs/reel (D=180mm)



Tape Specifications (mm)							
Width	Ao	Bo	Do	D ₁ (Min)	E ₁	F	Ko
12mm	*	*	1.5+0.1/-0.0	1.0	1.75±0.1	5.5±0.05	*
Width	P1	P2	P0	T (Max)	T1 (Max)	T2 (Max)	W (Max)
12mm	4.0±0.1	2.0±0.05	4.0±0.1	0.6	0.1	6.5	12.3
*Note: Compliant to EIA-481							

Dimensions: mm



Reel Specifications (mm)							
Width	Qty/Reel	A (Nom)	B (Min)	C (Min)	D (Min)	N (Min)	*W ₁
12mm	1000	178	1.5	13.0+0.5/-0.2	20.2	50	12.4+2.0/-0.0
*Note: Measured at Hub							

Dimensions: mm